



Initial Product/Process Change Notification

Document #: IPCN25297Z

Issue Date: 17 May 2023

Title of Change:	Transfer wafer fabrication from Gresham to Aizu for NCD570x family of gate driver products.	
Proposed Changed Material First Ship Date:	07 Mar 2024 or earlier if approved by customer	
Current Material Last Order Date:	N/A <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i>	
Current Material Last Delivery Date:	N/A <i>The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory</i>	
Product Category:	Active components – Integrated circuits	
Contact information:	Contact your local onsemi Sales Office or David.Craig@onsemi.com	
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Additional Reliability Data:	Contact your local onsemi Sales Office or Nicky.Siu@onsemi.com	
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 6 months prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com >.	
Change Category		
Category	Type of Change	
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor	
Equipment	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.	
Description and Purpose:		
Change wafer fab and background site from onsemi Gresham, Oregon USA to onsemi Aizu, Japan.		
	From	To
Fab Site	onsemi Gresham, Oregon USA	onsemi Aizuwakamastu, Japan
Equipment/tool	Gresham fab toolset	Aizu fab toolset
There are no product material changes as a result of this change.		



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Reason / Motivation for Change:	Process/Materials Change		
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device will be qualified and validated based on the same Product Specification. No anticipated impacts.		
Sites Affected:			
onsemi Sites		External Foundry/Subcon Sites	
onsemi Aizu, Japan		None	
Marking of Parts/ Traceability of Change:	Part marking shows assembly site and assembly date. Assembly lot (marked on reel and shipping boxes) is traceable to source wafer fab.		
Reliability Data Summary:			
QV DEVICE NAME NCV5700DR2G RMS O88670 (HAST, HTOL, HTSL, RSH, TC, UHAST) and O89114 (ELFR) PACKAGE SOIC16			
Test	Specification	Condition	Interval
High Temperature Operating Life	JESD22-A108	Ta= 125 °C, 100 % max rated Vcc	2016 hrs
Early Life Failure Rate	AECQ100-008	Ta= 125 °C, 100 % max rated Vcc	48 hrs
High Temperature Storage Life	JESD22-A103	Ta= 150°C	2016 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C, Pre TC, uHAST, HAST for surface mount pkgs only	
Temperature Cycling	JESD22-A104	Ta= -65 °C to + 150 °C	1000 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Resistance to Solder Heat	JESD22- B106	Ta = 265°C, 10 sec Required for through hole devices only	
Electrical Characteristics Summary:			
Electrical characteristics are not impacted.			

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Current Part Number	New Part Number	Qualification Vehicle
NCV5700DR2G	NA	NCV5700DR2G
NCV5701ADR2G	NA	NCV5700DR2G
NCV5701CDR2G	NA	NCV5700DR2G
SNCV5700DR2G	NA	NCV5700DR2G
NCV5707BDR2G	NA	NCV5700DR2G



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NCV5705BDR2G	NA	NCV5700DR2G
NCV5703DDR2G	NA	NCV5700DR2G
NCV5703CDR2G	NA	NCV5700DR2G
NCV5703BDR2G	NA	NCV5700DR2G
NCV5703ADR2G	NA	NCV5700DR2G
NCV5702DR2G	NA	NCV5700DR2G
NCV5701BDR2G	NA	NCV5700DR2G